

HVM**

Features

Controlled avalanche characteristic combined with the ability to dissipate reverse power
 Plastic package has underwriters laboratory lammability classification 94V-0
 Low forward voltage drop
 Typical IR less than 1 uA
 High overload surge capability
 High temperature soldering guaranteed
 260-C/10s/.375" (9.5mm) lead length at 5 lbs., (2.3kg) tension



Mechanical data

Case: Reliable low cost construction utilizing molded plastic technique
Terminals: Axial leads. Solderable per MIL-STD-202 Method 208
Polarity: Color band denotes cathode end
Weight: 2.6 g

We declare that the material of product compliance with RoHS requirements.

1. Electrical Characteristic

Maximum Ratings & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

| Parameter | Symbol | HVM5 | HVM8 | HVM10 | HVM12 | HVM15 | HVM16 | HVM18 | Unit |
|--|----------------|-------------|------|-------|-------|-------|-------|-------|------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 5 | 8 | 10 | 12 | 15 | 16 | 18 | KV |
| Maximum RMS voltage | V_{RMS} | 3.5 | 5.6 | 7 | 8.4 | 10.5 | 11.2 | 12.6 | KV |
| Maximum DC blocking voltage | V_{DC} | 5 | 8 | 10 | 12 | 15 | 16 | 18 | KV |
| Maximum average forward rectified current 0.375" (9.5mm) lead length at TA=55-C | I_o | 450 | | | | | | | mA |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 30 | | | | | | | A |
| Operating junction and storage temperature range | T_J, T_{STG} | -40 to +130 | | | | | | | -C |

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

| Parameter | Symbol | HVM5 | HVM8 | HVM10 | HVM12 | HVM15 | HVM16 | HVM18 | Unit |
|---|--------|------|------|-------|-------|-------|-------|-------|---------|
| Maximum instantaneous forward voltage at 1A | V_F | 10.0 | | 12 | | 14 | | 16 | V |
| Maximum DC reverse current at rated DC blocking voltage TA=25-C | I_R | 10.0 | | | | | | | μA |

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2.Ratings and Characteristic Curves(TA= 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

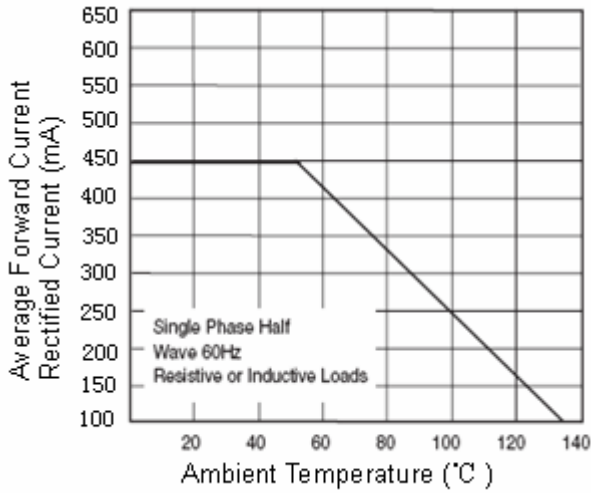


Fig. 2 - Maximum Non-Repetitive Peak Forward Surge Current

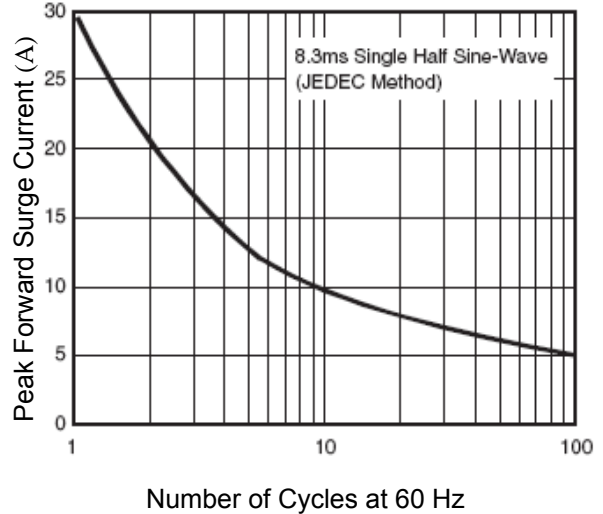


Fig. 3 - Typical Reverse Characteristics

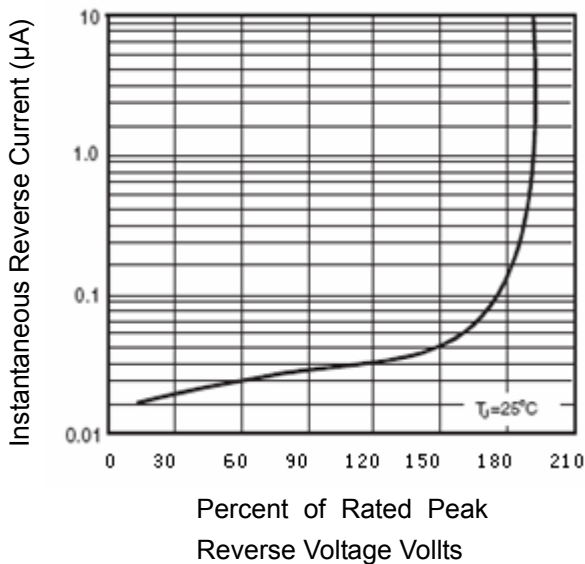
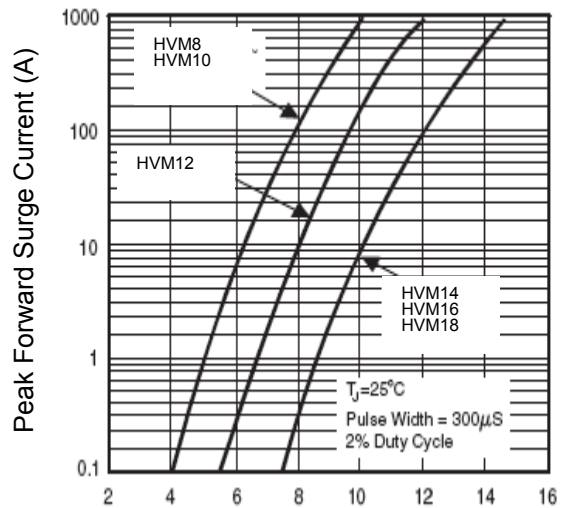
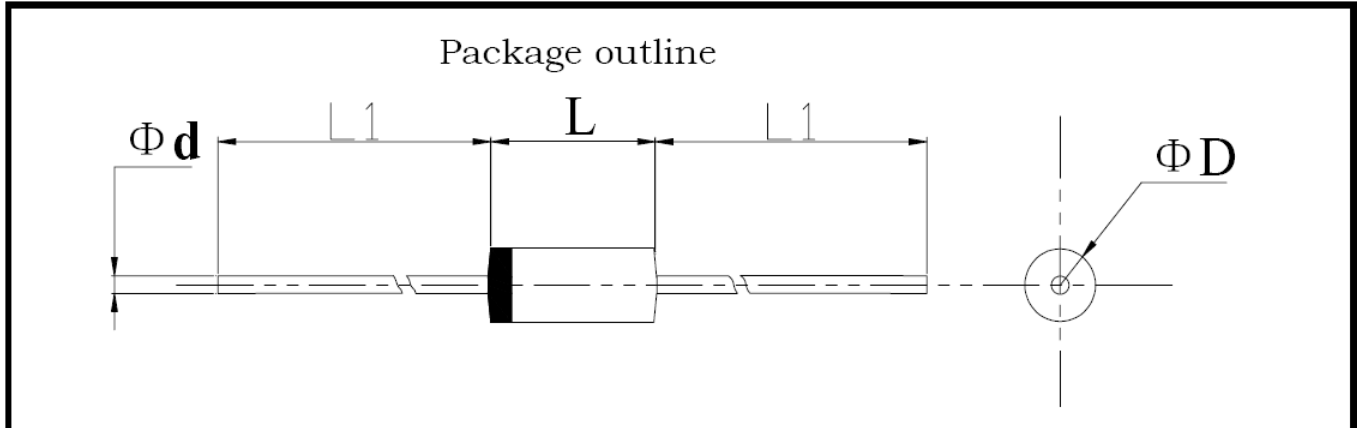


Fig.4-Typical Instantaneous Forward Characteristics



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3. dimension:



| Dimensions | | | | | Note: HVM molded plastic case The marking band indicates the cathode |
|------------|--------|-------|------|------|--|
| | inches | | mm | | |
| | Min. | Max. | Min. | Max. | |
| L | 0.768 | 0.886 | 19.5 | 22.5 | |
| L1 | 0.787 | - | 20 | - | |
| ΦD | 0.291 | 0.299 | 7.4 | 7.6 | |
| Φd | 0.041 | 0.051 | 1.0 | 1.3 | |

塑封生产线高压硅堆产品包装规范

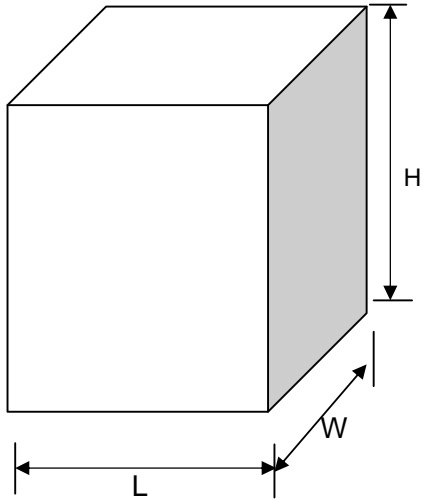
文件编号:Leiditech/M06-051

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5.1.3 外箱

材料: 双瓦楞纸



单位: mm

| | L | W | H |
|----|-------|-------|-------|
| 尺寸 | 475±2 | 335±2 | 380±4 |

5.2. 包装数量

5.2.1

袋装要求:

每个塑料袋内装50PCS不打端子的高压硅堆或双向二极管、一张合格证、一袋干燥剂;

每个塑料袋内装20PCS打端子的高压硅堆或双向二极管、一张合格证、一袋干燥剂;

5.2.2

盒装要求:

每盒装16代不打端子的高压硅堆或双向二极管

每盒装25代打端子的高压硅堆或双向二极管

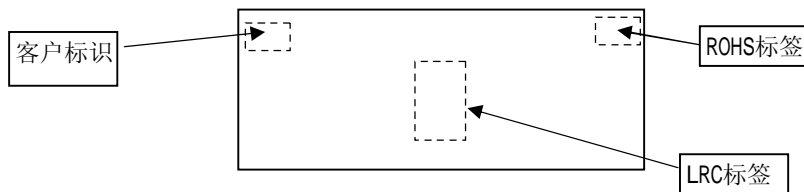
5.2.3

外箱要求:

每箱装10个内盒

5.2.4

标签要求:



塑封生产线高压硅堆产品包装规范

文件编号: Leiditech/M06-051

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5.3 产品出厂检验报告

每批出货时, 需要附上出厂检验报告

5.4 环保标签:



5.5. 无卤 (无卤产品才贴)



塑封生产线高压硅堆产品包装规范

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6、版式次更新记录

| 版次 | 更新记录 | 更新作者 | 更新日期 |
|----|------|------|------------|
| 1 | 第一版 | 余波 | 2011年9月28日 |

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4.Update Record

| 版次 | 更新记录 | 更新作者 | 更新日期 |
|----|------|------|-----------|
| 1 | 第一版 | 余波 | 2010-5-25 |
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